

## **AMENDMENTS TO THE CLAIMS:**

The following listing of claims replaces all prior versions of the claims.

1. (Currently Amended) A surface-mounted electronic component module comprising:

a wiring substrate having wiring patterns formed on one side and external connection terminals formed on the other side, the wiring patterns and the external connection terminals being connected with each other via holes or through holes;

a plurality of electronic component devices mounted on the one side of the wiring substrate, ~~at least one of~~

wherein the plurality of electronic component devices ~~being~~ include a surface acoustic wave filter that is fastened face up to the one side of the wiring substrate, and having a connection terminal, and a semiconductor chip that is fastened face down to the one side of the wiring substrate;

a bonding wire connecting the connection terminal of the ~~one of the plurality of electronic component devices~~ surface acoustic wave filter with ~~another of the plurality of electronic component devices~~ the semiconductor chip or with one of the wiring patterns formed on the one side of the wiring substrate, the bonding wire having an inductance that eliminates ripples in a frequency band characteristic of the ~~one electronic component device~~ surface acoustic wave filter to which one terminal of the bonding wire is connected; and

an exterior resin layer formed on the wiring substrate which covers the plurality of electronic component devices, and the bonding wire.

2. (Canceled)

3. (Currently Amended) The surface-mounted electronic component module according to claim 1, wherein the ~~electronic component device~~ surface acoustic wave filter fastened face up to the one side of the wiring substrate is fastened to the wiring substrate by a bond made of conductive paste.

4. (Canceled)

5. (Currently Amended) A surface-mounted electronic component module comprising:

a wiring substrate having wiring patterns formed on one side and external connection terminals formed on the other side, the wiring patterns and the external connection terminals being connected with each other by via holes or through holes;

a semiconductor chip mounted face up on the one side of the wiring substrate, having a connection terminal, and forming a switch for changing over the opening/closing of radio frequency transmission/ reception signals and a decoder circuit for controlling the switch changeover operations;

a surface acoustic wave filter fastened face up and mounted on the one side of the wiring substrate, and electrically connected to the switch;

a bonding wire having one terminal connected to the surface acoustic wave filter and the other terminal connected to the connection terminal of the semiconductor chip, the bonding wire having a specific inductance that eliminates ripples in a frequency band characteristic of the surface acoustic wave filter; and

an exterior resin layer formed on the wiring substrate which covers the semiconductor chip, the surface acoustic wave filter and the bonding wire.

6. (Canceled)

7. (Previously Presented) The surface-mounted electronic component module according to claim 5, wherein the semiconductor chip mounted face up on the one side of the wiring substrate, is fastened to the wiring substrate by a bond made of conductive paste.

8. (Withdrawn) A method for manufacturing a surface-mounted electronic component module comprising the steps of:

providing a wiring substrate having wiring patterns formed on one side and external connection terminals formed on the other side, the wiring patterns on the one side and the external connection terminals on the other side being connected with each other by via holes or through holes;

providing a semiconductor chip having connection terminals disposed on at least the same surface;

providing a surface acoustic wave filter having connection terminals disposed on at least the same surface, the surface acoustic wave filter having a closed gap immediately above the portion where a transducer is formed;

fastening both or at least one of the semiconductor chip and the surface acoustic wave filter to the wiring pattern surface of the wiring substrate such that the connection terminal does not face the wiring pattern surface;

making by wire at least one of three connections, connection between the connection terminal of the semiconductor chip and the wiring pattern of the wiring substrate, connection between the connection terminal of the surface acoustic wave filter and the wiring pattern of the wiring substrate, and connection between the

connection terminal of the semiconductor chip and the connection terminal of the surface acoustic wave filter; and

coating the wiring substrate with exterior resin in such a manner as to cover the semiconductor chip and the surface acoustic wave filter fastened to the wiring substrate.

9. (Previously Presented) The module of claim 1, wherein the inductance of the bonding wire is 1 nh/mm.

10. (Previously Presented) The module of claim 5, wherein the inductance of the bonding wire is 1nh/mm.

11. (New) A surface-mounted electronic component module comprising:  
a wiring substrate having wiring patterns formed on one side and external connection terminals formed on the other side, the wiring patterns and the external connection terminals being connected with each other via holes or through holes;

a plurality of electronic component devices mounted on the one side of the wiring substrate,

wherein the plurality of electronic component devices include a surface acoustic wave filter, which is fastened face down to the one side of the wiring substrate, having a connection terminal, and a semiconductor chip, which is fastened face up to the one side of the wiring substrate;

a bonding wire connecting the connection terminal of the surface acoustic wave filter with the semiconductor chip or with one of the wiring patterns formed on the one side of the wiring substrate, the bonding wire having an inductance that eliminates ripples in a frequency band characteristic of the semiconductor chip, to which one terminal of the bonding wire is connected; and

an exterior resin layer formed on the wiring substrate which covers the plurality of electronic component devices, and the bonding wire.